

Massive Electro-Pyrotechnic Initiator Chip Resistor

FEATURES

process

SMD version only

Case size 0805

Surface mount design for standard assembly

Active area designed upon performances

• Ohmic value: 2 Ω to 8 Ω ± 10 % (typical) ⁽²⁾

please see www.vishay.com/doc?99912

chemistry and active areas geometry

Very predictable, reproducible and reliable behavior

Compatibility with pyrotechnic element has to be tested in

Material categorization: for definitions of compliance

This datasheet provides information about parts that are RoHS-compliant and / or parts that are non-RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant.

For ohmic value < 3 Ω the tolerance will be discussed with Vishay

Please see the information / tables in this datasheet for details ⁽¹⁾ Ignitor performances are dependent on both pyrotechnic primer

Easy set up by design of firing levels

Firing energy down to 1.0 mJ ⁽¹⁾

Firing time down to 250 µs

Joule effect ignition

real environment

Notes

(2)

Sfernice



LINKS TO ADDITIONAL RESOURCES



The Massive Electro-Pyrotechnic Initiator Chips (MEPIC) are resistors dedicated to pyrotechnic applications. The MÉPIC resistors are the Surface Mount Device (SMD) variants from the established NiCr on FR type substrate technology from Vishay Sfernice. The standard case geometry (SMD) enables the implementation of assembly process commonly used in the electronic component industry (pick and place, reflow soldering on flat PCB used as header) providing high productivity. The principle of MEPIC is to convert electrical energy into heat in a precise electro-thermal profile for the purpose of initiating a series of pyrotechnic events in a controlled energetic reaction. In the mining industry this effect is commonly used for the ignition of electronic detonators (digital blasting). Other industries such as firework (e-match manufacturing) and demolition (various electric detonators) are also focused applications.

The MEPIC design has been developed specifically to offer an alternative to the Bridge Wire (BW) technology, insuring at least the same level of performances, while providing cost efficient assembly process and initiator design alternatives.

TECHNOLOGY

The MEPIC active area (heating zone) will be impregnated by the user with a primary pyrotechnic material (usually wet primer followed by drying) in such way to ensure an intimate contact for an optimum heat transfer of thermal energy. The geometry of the active area of the MEPIC, and both the primer chemistry and its impregnation method, will determine the global performances. Note that the active area of MEPIC shall not be put in direct contact with explosive powder as grain size will not ensure intimate contact and will induce non reproducible and non reliable performances.

The two main characteristics of a MEPIC resistor are their "All Fire" (AF) and "No Fire" (NF) performances:

- "All Fire" (AF) represents the command pulse where the major amount of the dissipated energy will be transferred to the primer to generate the ignition. Customer will have to provide Vishay Sfernice with "All Fire" conditions, usually with capacitance discharge parameters or with Minimum Current or Voltage and corresponding short pulse duration.
- "No Fire" (NF) represents the immunity of the resistor with primer to the environmental electro-magnetic pollution and electric continuity test, where the major amount of the dissipated energy will be transferred to the substrate to ensure no ignition. Customer will have to provide Vishay Sfernice with "No Fire" conditions, usually maximum current or voltage and corresponding longest duration. In case of applicable capacitance discharge test the parameters shall also be provided.

ASSEMBLY PRECAUTIONS

In order to obtain reproducible ignition performances it is important that the assembly process fulfills the following criteria:

- Do not use iron soldering method to mount the MEPIC on its header because uncontrolled amount of solder could impact the heat transfer (potential misfire or ignition delay) and local over heating may damage the MEPIC (deformation that may cause active area cracks).
- Take specific precautions, such as no air bubble during preparation and application of primer, in order to ensure the intimate contact of pyrotechnic primer and MEPIC active area (potential misfire).
- Take specific handling precaution in order not to damage MEPIC active area (ex: pickup head design for pick and place or specific fixing tools in the entire assembly process.
- All along the assembly process, take specific care to extreme thermo-mechanic stress that could be applied to the MEPIC (such as stress induced during over molding) because the active area of MEPIC is subjected to crack (and generate unstable resistance value).
- The MEPIC reliability is only guaranteed for one single reflow profile.
- In case of necessity to dismantle a MEPIC, another MEPIC must be used (no rework is allowed).
- Pay specific attention to the cleaning process after reflow soldering in order not to damage the active area and to keep it clean from various pollutions.

1

THIS DOCUMENT IS SUBJECT TO CHANGE WITHOUT NOTICE. THE PRODUCTS DESCRIBED HEREIN AND THIS DOCUMENT ARE SUBJECT TO SPECIFIC DISCLAIMERS, SET FORTH AT www.vishav.com/doc?91000





Vishay Sfernice

STANDARD ELECTRICAL SPECIFICATIONS

MODEL SIZE / CASE DESIGNATION (1)		$\begin{array}{c} \textbf{RESISTANCE RANGE} \\ \Omega \end{array}$	RESISTANCE TOLERANCE %	
MEPIC (SMD)	0805	2 to 8	10 to 30	

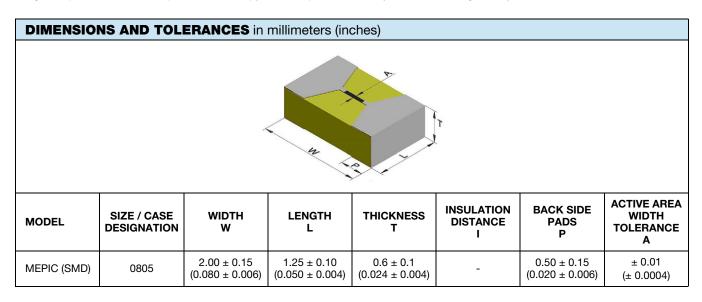
Note

⁽¹⁾ Detailed dimensions are specified in Dimensions and Tolerances table

RANGE OF IGNITION PERFORMANCES							
MODEL	"NO FIRE" CURRENT A	"NO FIRE" DURATION s	"ALL FIRE" CURRENT A	IGNITION TIME ms	"ALL FIRE" ENERGY μJ		
MEPIC (SMD)	0.5 to 1.2	2 to 10	Down to 1	Down to 0.25	Down to 1000		

Note

· Ignition performances are dependent on both pyrotechnic primer chemistry and active area geometry



CONSTRUCTION

- Substrate: epoxy based (FRx type)
- Resistive element: NiCr
- Terminations: SMD wraparound
- Tin plated copper

HOW TO GET THE RIGHT MEPIC

Each MEPIC will have to be adapted to customer pyrotechnic primer chemistry (energetic material). To reach the right MEPIC design it is necessary to work by "iterations". Upon receipt of the MEPIC Design Guide duly filled, an initial sampling lot is given to customer (along with a MEPIC reference) so he can provide "No Firing" / "All Firing" performances obtained after first testing. After the analysis of these first test results a new set of samples will be proposed (eventually tooling charges will be necessary) in order to get closer to the customer requirements. It may be several iterations until the right design is found. It may also happen that all requirements cannot be fulfilled simultaneously and then a compromise will be necessary between MEPIC design and customer pyrotechnic primer chemistry or ignition parameters.

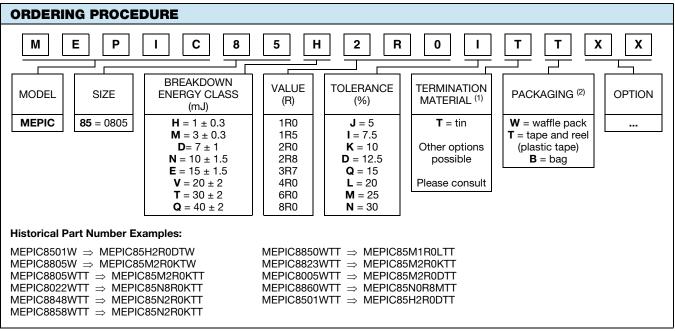
When the iterations are finished, which means that the design is validated with total or partial requirements fulfilled, Vishay Sfernice will design a final set of photomasks for serial production.



www.vishay.com

MEPIC

Vishay Sfernice



Notes

• MEPIC being a semi-custom product, please fill EPIC / MEPIC Design Guide (<u>www.vishay.com/doc?53045</u>) and send to <u>sferthinfilm@vishay.com</u> to get appropriate part number

⁽¹⁾ Tin termination finish only valid for reflow soldering

⁽²⁾ Customer assembly process requirement:

- Waffle pack for manual placing on PCB

- Tape and reel for automatic pick and place

- Bag for bowl feeding



Vishay

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Hyperlinks included in this datasheet may direct users to third-party websites. These links are provided as a convenience and for informational purposes only. Inclusion of these hyperlinks does not constitute an endorsement or an approval by Vishay of any of the products, services or opinions of the corporation, organization or individual associated with the third-party website. Vishay disclaims any and all liability and bears no responsibility for the accuracy, legality or content of the third-party website or for that of subsequent links.

Vishay products are not designed for use in life-saving or life-sustaining applications or any application in which the failure of the Vishay product could result in personal injury or death unless specifically qualified in writing by Vishay. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

© 2025 VISHAY INTERTECHNOLOGY, INC. ALL RIGHTS RESERVED

Revision: 01-Jan-2025

1